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- (71) **Applicant:** GENERAL ELECTRIC COMPANY
[US/US]; 1 River Road, Schenectady, NY 12345 (US).
- (72) **Inventor:** KANKANAM, Gamage, Sisira; 1055 Mission
Court Crown Estate, Fremont, CA 94539 (US).
- (74) **Agents:** CONKLIN, Mark, A. et al.; General Electric
Company, Global Patent Operation, 2 Corporate Drive,
Suite 648, Shelton, CT 06484 (US).
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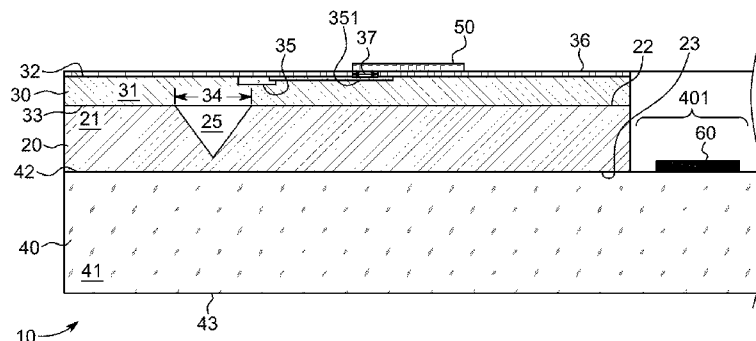
(54) **Title:** CATHETER DIE AND METHOD OF FABRICATING THE SAME

FIG. 1

(57) **Abstract:** A catheter die (10) is provided and includes a device layer (20) defining a cavity (25) and including a piezoresistive pressure sensor (35) operably disposed proximate to the cavity and an insulator (30) having an opening and being disposed on an upper surface of the device layer such that a portion of the piezoresistive pressure sensor is exposed through the opening. The catheter die further includes an insulation layer (40) bonded to a lower surface of the device layer and first and second bond pads (50, 60), the first bond pad being electrically coupled to the portion of the piezoresistive pressure sensor via the opening and the second bond pad being disposed on the insulation layer.